

CMPA1E1F060F Rev. V1

Features

Saturated Power: 50 W
Power Added Efficiency: 38%
Large Signal Gain: 25 dB
Small Signal Gain: 29 dB
Input Return Loss: -16 dB
Output Return Loss: -10 dB

IM3: -25dBc (25W P_{total}) Pulsed/CW Operation

Applications

Satellite Uplink

Common Data Links

Description

MACOM's CMPA1E1F060F is a 50 W, MMIC HPA utilizing MACOM's high performance, 0.15 μ m GaN on SiC production process. The CMPA1E1F060F operates from 13.4 – 15.5 GHz and targets lower Ku-band radar applications, as well as, satellite uplinks and common datalink applications. Under saturation, the CMPA1E1F060F achieves 50 W of typical output with 25 dB of large signal gain and > 38% power-added efficiency. Targeting an IM3 level of -25 dBc or better, this HPA delivers 25 W of output power with 31 dB of gain and > 32% power-added efficiency.

Above stated performance is typical across frequency at 25°C. Please reference included specification tables and performance curves for additional details.

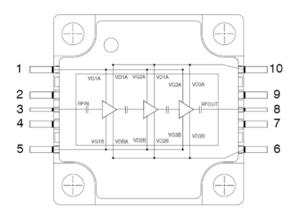
Packaged in a 15x15 mm bolt-down, flange package, the CMPA1E1F060F provides superior RF performance and thermal management allowing customers to improve SWaP-C benchmarks in their next-generation systems.

Ordering Information

Part Number	Package (MOQ/ Mult)
CMPA1E1F060F	Tray (10/10)
CMPA1E1F060F-AMP	Sample Board (1/1)



Functional Schematic



Pin Configuration¹

Pin #	Function
1, 5	VG
2, 4, 7, 9	RF/DC Ground
3	RF Input
6, 10	VD
8	RF Output

 The base of the package must be connected to RF, DC and thermal ground.



RF Electrical Specifications: $V_D = 28 \text{ V}$, $I_{DQ} = 650 \text{ mA}$, CW, $T_C = 25 ^{\circ}\text{C}$, $Z_0 = 50 \Omega$

Parameter	Test Conditions	Frequency (GHz)	Units	Min.	Тур.	Max.
Output Power		13.4 13.75 14.5 15.5	dBm	47.0 46.8 46.5 46.0	48 48 47.5 47	_
Power Added Efficiency	Pin = 22 dBm	13.4 13.75 14.5 15.5	%	30 30 29 29	37 36 35 36	1
Large Signal Gain		13.4 13.75 14.5 15.5	dB		26 26 25.5 25	I
Small Signal Gain			dB		29	1
Input Return Loss	Pin = -20 dBm	13.4 - 15.5	dB	_	-16	_
Output Return Loss			dB		-10	_
IM3	Pout/Tone=41dBm; Spacing=300MHz	13.75 14.5 15.5	dBc	_	-25 -25 -25	_

DC Electrical Specifications:

Parameter		Min.	Тур.	Max.
Drain Voltage		_	28	
Gate Voltage	V	_	-2.1	_
Quiescent Drain Current		325	650	1000
Saturated Drain Current		_	5.0	_



CMPA1E1F060F Rev. V1

Recommended Operating Conditions

Parameter	Symbol	Unit	Min.	Тур.	Max.
Input Power	P _{IN}	dBm		22	
Drain Voltage	V_D	V		28	
Gate Voltage	V_{G}	V		-2.1	
Quiescent Drain Current	I _{DQ}	mA		650	
Case Temperature	T _C	°C	-40		+85

Absolute Maximum Ratings^{2,3}

Parameter	Symbol	Unit	Min.	Max.
Input Power	P _{IN}	dBm		24
Drain to Source Breakdown Voltage	BV _{DS}	V		84
Drain Voltage	V_D	V		28
Gate Voltage	V_{G}	V	-8	+2
Drain Current	I _D	Α		7.8
Gate Current	I _G	mA		15
Dissipated Power @ +85°	P _{DISS}	W		101
VSWR		Ratio		5:1
Junction Temperature (MTTF > 1E6 Hrs)	TJ	°C		+225
Storage Temperature	T _{STG}	°C	-65	+150
Mounting Temperature (30 seconds)	T _M	°C		+260
Screw Torque	τ	in-oz		40

^{2.} Exceeding any one or combination of these limits may cause permanent damage to this device.

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

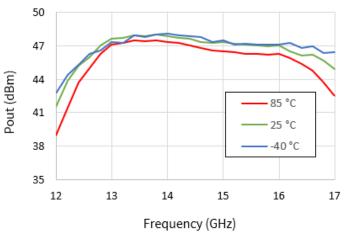
^{3.} MACOM does not recommend sustained operation near these survivability limits.



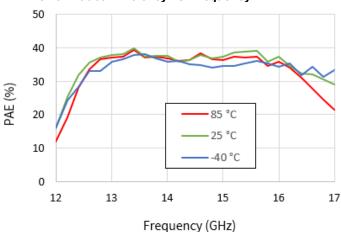
Typical Performance Curves - Large Signal over Temperature:

 $V_D = 28 \text{ V}, I_{DQ} = 650 \text{ mA}, CW, P_{IN} = 22 \text{ dBm}$

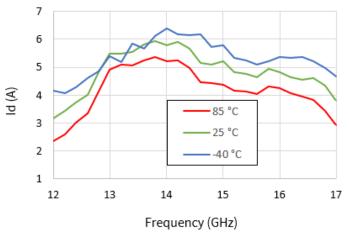
Output Power vs. Frequency



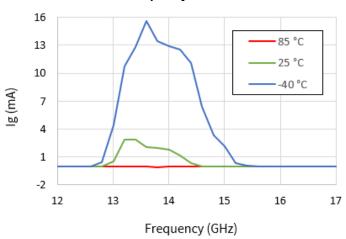
Power-Added Efficiency vs. Frequency



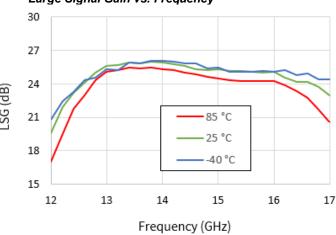
Drain Current vs. Frequency



Gate Current vs. Frequency



Large Signal Gain vs. Frequency



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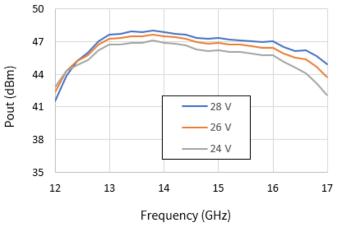
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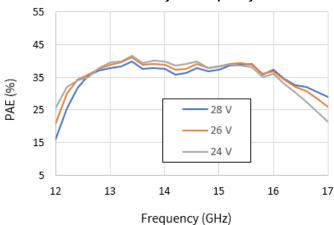
Typical Performance Curves - Large Signal over V_D:

 I_{DQ} = 650 mA, CW, P_{IN} = 22 dBm, T_{C} =25°C

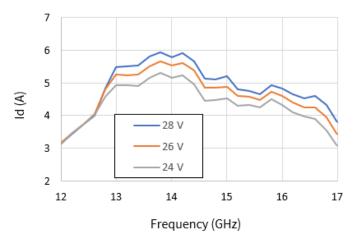
Output Power vs. Frequency



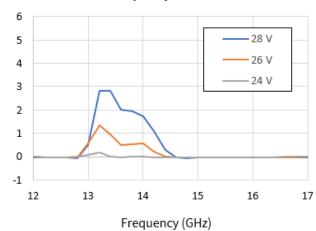
Power-Added Efficiency vs. Frequency



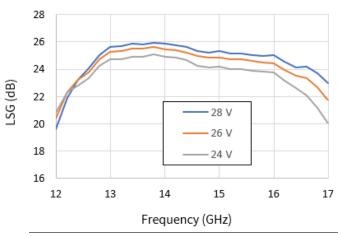
Drain Current vs. Frequency



Gate Current vs. Frequency



Large Signal Gain vs. Frequency



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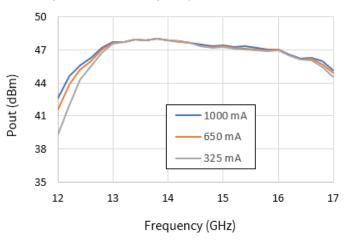
lg (mA)



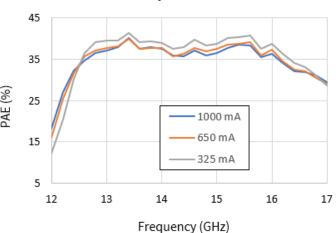
Typical Performance Curves - Large Signal over IDQ:

 $V_D = 28 \text{ V}, \text{ CW}, P_{IN} = 22 \text{ dBm}, T_C = 25^{\circ}\text{C}$

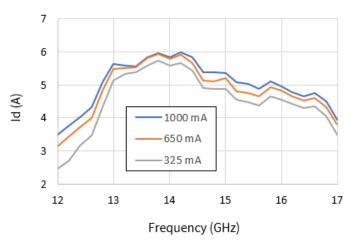
Output Power vs. Frequency



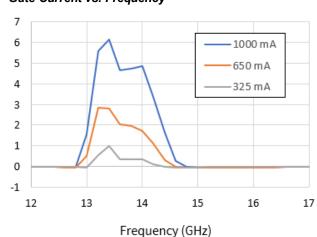
Power-Added Efficiency



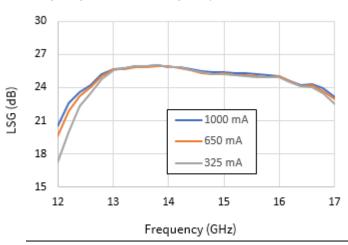
Drain Current vs. Frequency



Gate Current vs. Frequency



Large Signal Gain vs. Frequency



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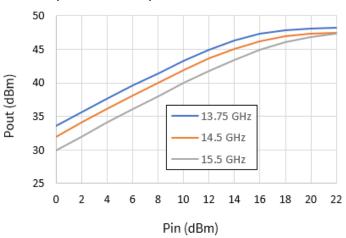
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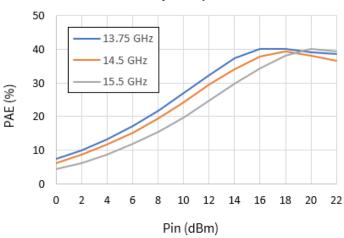
Typical Performance Curves - Drive-Up over Frequency:

 $V_D = 28 \text{ V}, I_{DQ} = 650 \text{ mA}, \text{ CW}, T_C = 25^{\circ}\text{C}$

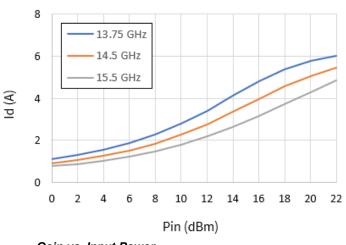
Output Power vs. Input Power



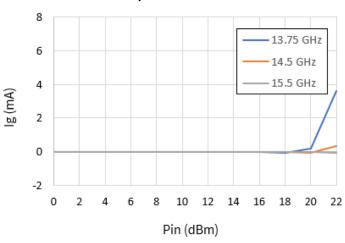
Power-Added Efficiency vs. Input Power



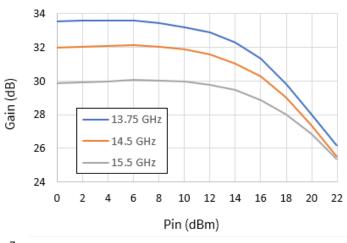
Drain Current vs. Input Power



Gate Current vs. Input Power



Gain vs. Input Power



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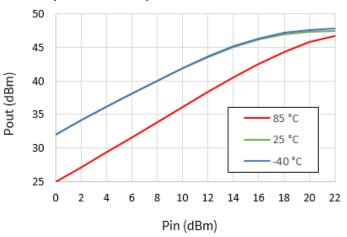
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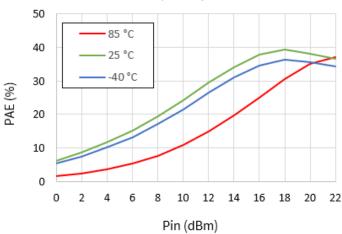
Typical Performance Curves - Drive-Up over Temperature:

 V_D = 28 V, I_{DQ} = 650 mA, CW, Frequency: 14.5GHz

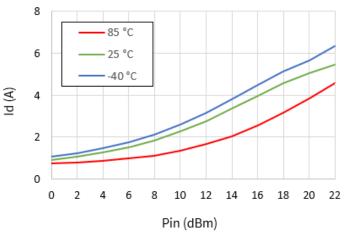
Output Power vs. Input Power



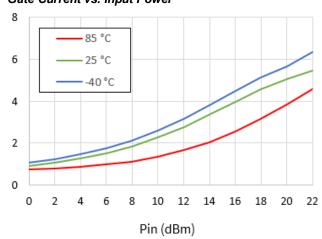
Power-Added Efficiency vs. Input Power



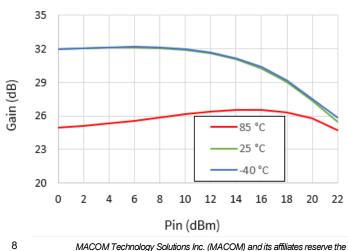
Drain Current vs. Input Power



Gate Current vs. Input Power



Gain vs. Input Power



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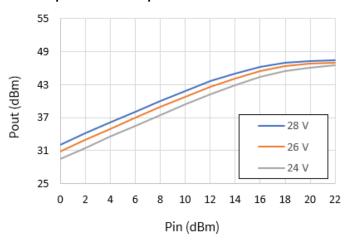
lg (mA)



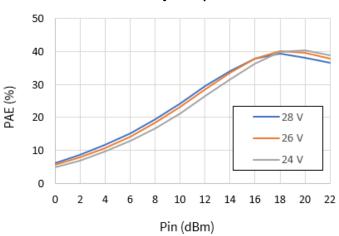
Typical Performance Curves - Drive-Up over V_D:

 I_{DQ} = 650 mA, CW, T_{C} = 25°C, Frequency: 14.5GHz

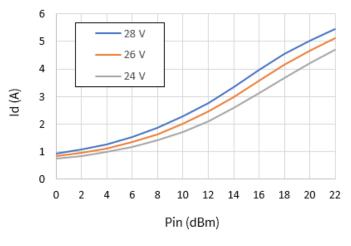
Output Power vs. Input Power



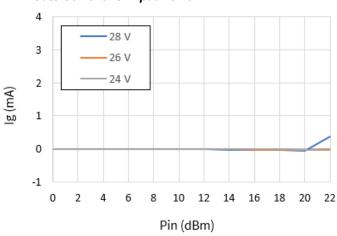
Power-Added Efficiency vs. Input Power



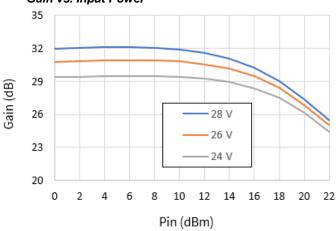
Drain Current vs. Input Power



Gate Current vs. Input Power



Gain vs. Input Power



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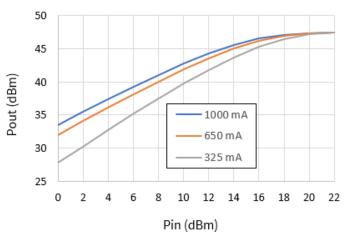
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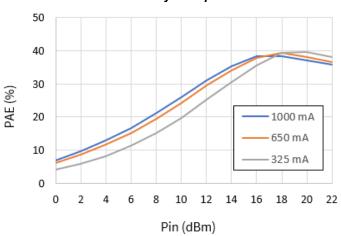
Typical Performance Curves - Drive-Up over IDQ:

 $V_D = 28 \text{ V}$, CW, $T_C = 25^{\circ}\text{C}$, Frequency: 14.5GHz

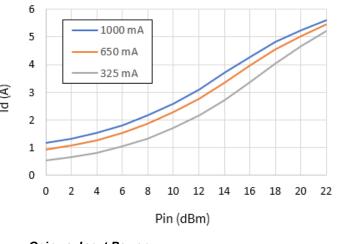
Output Power vs. Input Power



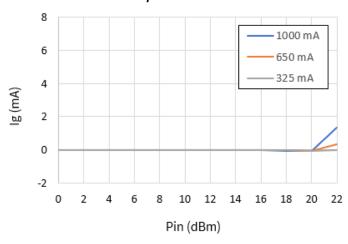
Power-Added Efficiency vs. Input Power



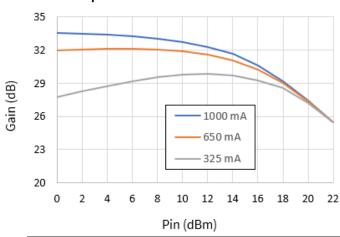
Drain Current vs. Input Power



Gate Current vs. Input Power



Gain vs. Input Power



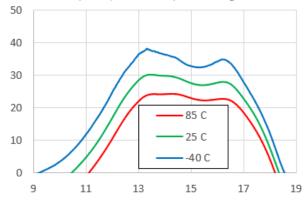


Typical Performance Curves - Small Signal over Temperature and $V_{\text{\tiny D}}$:

S21 (dB)

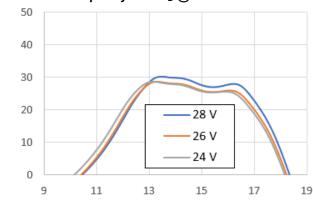
 I_{DQ} = 650 mA, CW, P_{IN} = -20 dBm





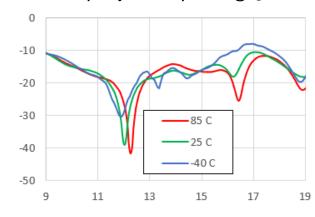
Frequency (GHz)

S21 vs. Frequency over V_D @ 25°C



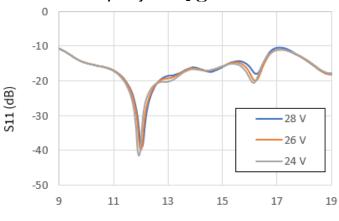
Frequency (GHz)

S11 vs. Frequency over Temperature @ V_D = 28 V



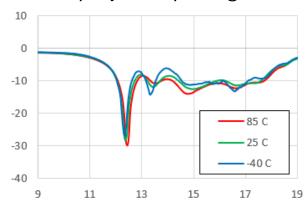
Frequency (GHz)

S11 vs. Frequency over V_D @ 25°C



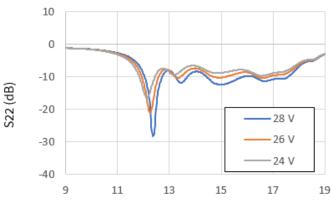
Frequency (GHz)

S22 vs. Frequency over Temperature @ V_D = 28 V



Frequency (GHz)

S22 vs. Frequency over V_D @ 25°C



Frequency (GHz)

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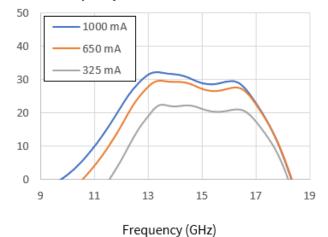
11



Typical Performance Curves - Small Signal over IDQ:

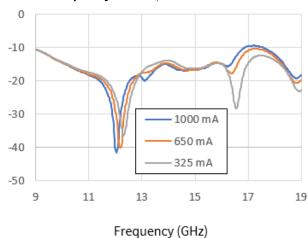
 $V_D = 28 \text{ V}, \text{ CW}, P_{IN} = 22 \text{ dBm}, T_C = 25^{\circ}\text{C}$

S21 vs. Frequency over IDQ

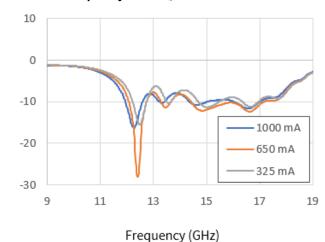


S11 vs. Frequency over IDQ

S11 (dB)



S22 vs. Frequency over IDQ

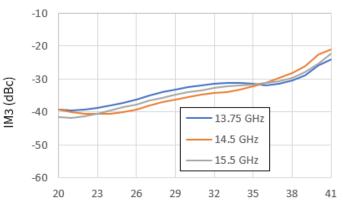




Typical Performance Curves - Linearity (IM3 and IM5)

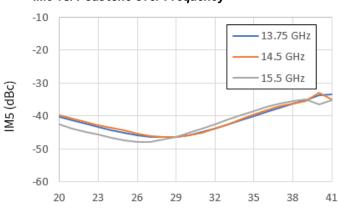
 V_D = 28 V, I_{DQ} = 650 mA, CW, P_{OUT} = 43 dBm, Frequency = 14.5 GHz, Tone Spacing = 10MHz, T_C = 25°C

IM3 vs. Pout/tone over Frequency



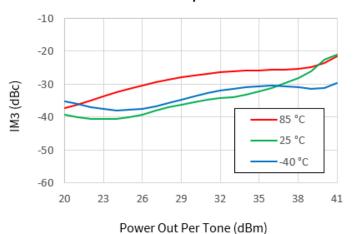
Power Out Per Tone (dBm)

IM5 vs. Pout/tone over Frequency

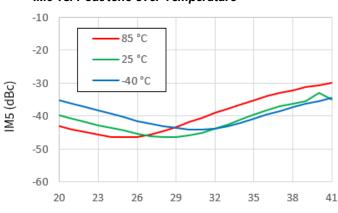


Power Out Per Tone (dBm)

IM3 vs. Pout/tone over Temperature

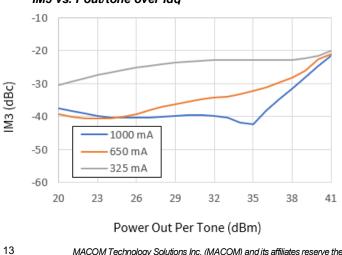


IM5 vs. Pout/tone over Temperature

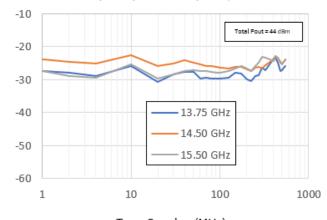


Power Out Per Tone (dBm)

IM3 vs. Pout/tone over Idq



IM3 vs. Tone Spacing over Frequency



Tone Spacing (MHz)

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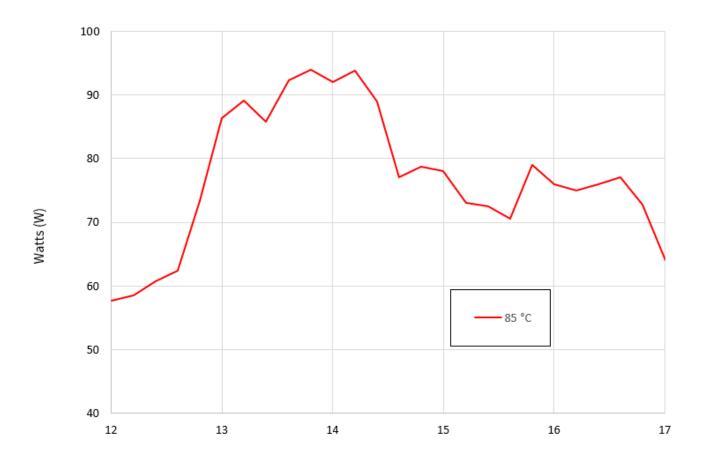
IM3 (dBc)



Thermal Characteristics

Parameter	Operating Conditions	Value
Operating Junction Temperature (T _J)	Freq = 2.5 GHz, V_D = 50 V, I_{DQ} = 500 mA, I_{DRIVE} = 1.8 A, P_{IN} = 32 dBm, P_{OUT} = 45.67 dBm, P_{DISS} = 55.5 W,	206.4°C
Thermal Resistance, Junction to Case (R _{0JC})	$T_{c} = 85^{\circ}C, CW$	2.187

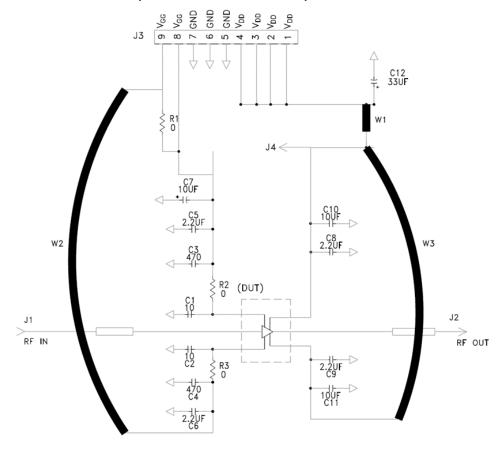
Power Dissipation vs. Frequency (T_c = 85°C)



Frequency (GHz)



Evaluation Board Schematic (CMPA1E1F060F-AMP)

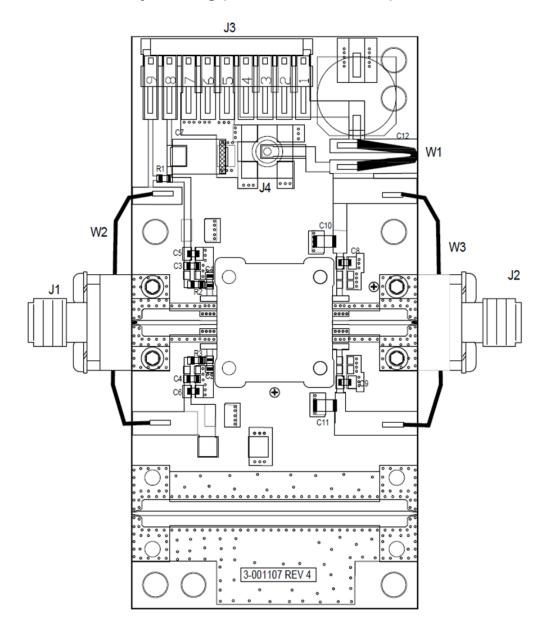


Parts List

Part	Value	Qty.
R1, R2, R3	RES 0 Ohm, 0603	3
C1,C2	CAP, 10PF, +/-5%, ATC600S	2
C3,C4	CAP, 470PF, 5%, 100V, 0603	2
C5,C6,C8,C9	CAP, 2.2UF	4
C7	CAP 10UF 16V TANTALUM, 2312	1
C10,C11	CAP, 10UF	2
C12	CAPACITOR, 33UF, 100V, Electrolytic	1
-	PCB, RO3003, .010 THK, HPHF Package	1
-	BASEPLATE 3.0x1.5x0.25 Cu	1
J1, J2	Connector SMA JACK (FEMALE) END LAUNCH CONNECTOR	2
J4	CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED	1
J3	HEADER RT>PLZ .1CEN LK 9POS	1
W1	WIRE, BLACK, 30 AWG	1
W2, W3	WIRE, BLACK, 22 AWG	2
U1	CMPA1E1F060F	1



Evaluation Board Assembly Drawing (CMPA1E1F060F-AMP)



Bias On Sequence

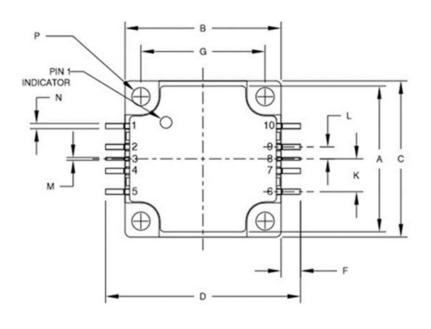
- 1. Ensure RF is turned-off
- 2. Apply pinch-off voltage of -5 V to the gate (V_G)
- 3. Apply nominal drain voltage (V_D)
- 4. Adjust Vg to obtain desired quiescent drain current (I_{DQ})
- Apply RF

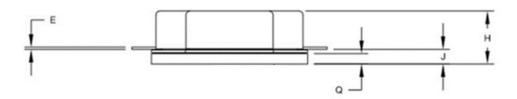
Bias Off Sequence

- 1. Turn RF off
- 2. Apply pinch-off to the gate $(V_G = -5 V)$
- 3. Turn off drain voltage (V_D)
- 4. Turn off gate voltage (V_G)



Mechanical Information



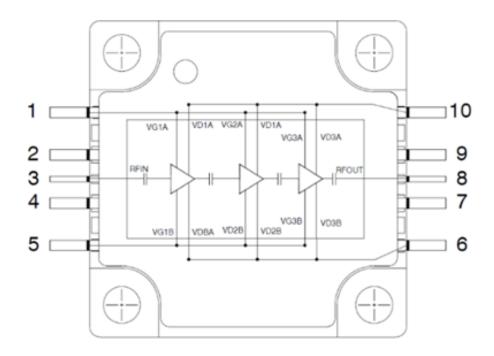


		INCHES			MILLIMETERS			
DIM	MIN	TYP	MAX	MIN	TYP	MAX		
Α	.555	.560	.565	14.10	14.22	14.35		
В	.595	.600	.605	15.11	15.24	15.37		
С	.595	.600	.605	15.11	15.24	15.37		
D	-	(.750)			(19.05)	-		
Ε	.006	.008	.010	0.15	0.20	0.25		
F	.065	.075	.085	1.66	1.91	2.16		
G	.473	.478	.483	12.01	12.14	12.27		
Н	.191	.203	.215	4.86	5.16	5.46		
J	.049	.056	.063	1.24	1.42	1.60		
K	.121	.126	.131	3.07	3.20	3.33		
L	.041	.046	.051	1.04	1.17	1.30		
М	.005	.010	.015	0.13	.25	0.38		
N	.015	.020	.025	0.38	.51	0.63		
Р	.065	.070	.075	1.65	1.78	1.90		
Q	.038	.040	.042	0.97	1.02	1.07		



Pin Description

Pin#	Name	Description
1	VG	Pins 1 and 5 must be electrically connected to the gate bias voltage.
2	GND	RF and DC ground
3	RF Input	RF Input. 50-ohm matched. Internally DC blocked.
4	GND	RF and DC ground
5	VG	Pins 1 and 5 must be electrically connected to the gate bias voltage.
6	VD	Pins 6 and 10 must be electrically connected to the drain bias voltage.
7	GND	RF and DC ground
8	RF Output	RF Output. 50-ohm matched. Internally DC blocked.
9	GND	RF and DC ground
10	VD	Pins 6 and 10 must be electrically connected to the drain bias voltage.
Paddle	GND	RF and DC ground





CMPA1E1F060F Rev. V1

Revision History

Rev	Date	Change Description
V1P	09/17/2024	Initial preliminary release.
V1	09/29/2025	Production release.



CMPA1E1F060F Rev. V1

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